

**RADIATION HARDENED  
 POWER MOSFET  
 SURFACE MOUNT (SMD-1)**

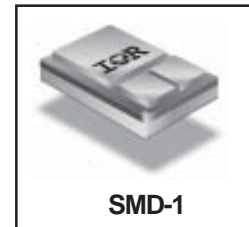
**IRHN9250  
 JANSR2N7423U  
 200V, P-CHANNEL**

REF: MIL-PRF-19500/662

**RAD Hard™ HEXFET® TECHNOLOGY**

**Product Summary**

Part Number	Radiation Level	RDS(on)	Id	QPL Part Number
IRHN9250	100K Rads (Si)	0.315Ω	-14A	JANSR2N7423U
IRHN93250	300K Rads (Si)	0.315Ω	-14A	JANSF2N7423U



International Rectifier's RADHard HEXFET™ technology provides high performance power MOSFETs for space applications. This technology has over a decade of proven performance and reliability in satellite applications. These devices have been characterized for both Total Dose and Single Event Effects (SEE). The combination of low Rds(on) and low gate charge reduces the power losses in switching applications such as DC to DC converters and motor control. These devices retain all of the well established advantages of MOSFETs such as voltage control, fast switching, ease of paralleling and temperature stability of electrical parameters.

**Features:**

- Single Event Effect (SEE) Hardened
- Low RDS(on)
- Low Total Gate Charge
- Proton Tolerant
- Simple Drive Requirements
- Ease of Paralleling
- Hermetically Sealed
- Surface Mount
- Ceramic Package
- Light Weight

**Absolute Maximum Ratings**

**Pre-Irradiation**

	Parameter		Units
Id @ VGS = -12V, TC = 25°C	Continuous Drain Current	-14	A
Id @ VGS = -12V, TC = 100°C	Continuous Drain Current	-9.0	
IDM	Pulsed Drain Current ①	-56	
PD @ TC = 25°C	Max. Power Dissipation	150	W
	Linear Derating Factor	1.2	W/°C
VGS	Gate-to-Source Voltage	±20	V
EAS	Single Pulse Avalanche Energy ②	500	mJ
IAR	Avalanche Current ①	-14	A
EAR	Repetitive Avalanche Energy ①	15	mJ
dv/dt	Peak Diode Recovery dv/dt ③	-41	V/ns
TJ	Operating Junction	-55 to 150	°C
TSTG	Storage Temperature Range		
	PCKG Mounting Surface Temp.	300 ( for 5s)	
	Weight	2.6 (typical)	g

For footnotes refer to the last page

**Electrical Characteristics @ T<sub>j</sub> = 25°C (Unless Otherwise Specified)**

	Parameter	Min	Typ	Max	Units	Test Conditions
BV <sub>DSS</sub>	Drain-to-Source Breakdown Voltage	-200	—	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = -1.0mA
ΔBV <sub>DSS</sub> /ΔT <sub>J</sub>	Temperature Coefficient of Breakdown Voltage	—	-0.24	—	V/°C	Reference to 25°C, I <sub>D</sub> = -1.0mA
R <sub>DSON</sub>	Static Drain-to-Source On-State Resistance	—	—	0.315	Ω	V <sub>GS</sub> = -12V, I <sub>D</sub> = -9.0A <sup>④</sup>
		—	—	0.33		V <sub>GS</sub> = -12V, I <sub>D</sub> = -14A <sup>④</sup>
V <sub>GS(th)</sub>	Gate Threshold Voltage	-2.0	—	-4.0	V	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -1.0mA
g <sub>fs</sub>	Forward Transconductance	4.0	—	—	S (S)	V <sub>DS</sub> > -15V, I <sub>DS</sub> = -9.0A <sup>④</sup>
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	—	—	-25	μA	V <sub>DS</sub> = -160V, V <sub>GS</sub> = 0V
		—	—	-250		V <sub>DS</sub> = -160V, V <sub>GS</sub> = 0V, T <sub>J</sub> = 125°C
I <sub>GSS</sub>	Gate-to-Source Leakage Forward	—	—	-100	nA	V <sub>GS</sub> = -20V
I <sub>GSS</sub>	Gate-to-Source Leakage Reverse	—	—	100		V <sub>GS</sub> = 20V
Q <sub>g</sub>	Total Gate Charge	—	—	200	nC	V <sub>GS</sub> = -12V, I <sub>D</sub> = -14A V <sub>DS</sub> = -100V
Q <sub>gs</sub>	Gate-to-Source Charge	—	—	45		
Q <sub>gd</sub>	Gate-to-Drain ('Miller') Charge	—	—	85		
t <sub>d(on)</sub>	Turn-On Delay Time	—	—	60	ns	V <sub>DD</sub> = -100V, I <sub>D</sub> = -14A, V <sub>GS</sub> = -12V, R <sub>G</sub> = 2.35Ω
t <sub>r</sub>	Rise Time	—	—	240		
t <sub>d(off)</sub>	Turn-Off Delay Time	—	—	225		
t <sub>f</sub>	Fall Time	—	—	220		
L <sub>S</sub> + L <sub>D</sub>	Total Inductance	—	4.0	—	nH	Measured from the center of drain pad to center of source pad
C <sub>iss</sub>	Input Capacitance	—	4200	—	pF	V <sub>GS</sub> = 0V, V <sub>DS</sub> = -25V f = 1.0MHz
C <sub>oss</sub>	Output Capacitance	—	690	—		
C <sub>rss</sub>	Reverse Transfer Capacitance	—	160	—		

**Source-Drain Diode Ratings and Characteristics**

	Parameter	Min	Typ	Max	Units	Test Conditions
I <sub>S</sub>	Continuous Source Current (Body Diode)	—	—	-14	A	
I <sub>SM</sub>	Pulse Source Current (Body Diode) <sup>①</sup>	—	—	-56		
V <sub>SD</sub>	Diode Forward Voltage	—	—	-3.6	V	T <sub>j</sub> = 25°C, I <sub>S</sub> = -14A, V <sub>GS</sub> = 0V <sup>④</sup>
t <sub>rr</sub>	Reverse Recovery Time	—	—	775	rS	T <sub>j</sub> = 25°C, I <sub>F</sub> = -14A, di/dt ≤ -100A/μs
Q <sub>Rr</sub>	Reverse Recovery Charge	—	—	7.2	μC	V <sub>DD</sub> ≤ -50V <sup>④</sup>
t <sub>on</sub>	Forward Turn-On Time	Intrinsic turn-on time is negligible. Turn-on speed is substantially controlled by L <sub>S</sub> + L <sub>D</sub> .				

**Thermal Resistance**

	Parameter	Min	Typ	Max	Units	Test Conditions
R <sub>thJC</sub>	Junction-to-Case	—	—	0.83	°C/W	soldered to a 1" square copper-clad board
R <sub>thJ-PCB</sub>	Junction-to-PC board	—	6.6	—		

**Note:** Corresponding Spice and Saber models are available on the G&S Website.

For footnotes refer to the last page

## Radiation Characteristics

## IRHN9250, JANSR2N7423U

International Rectifier Radiation Hardened MOSFETs are tested to verify their radiation hardness capability. The hardness assurance program at International Rectifier is comprised of two radiation environments. Every manufacturing lot is tested for total ionizing dose (per notes 5 and 6) using the TO-3 package. Both pre- and post-irradiation performance are tested and specified using the same drive circuitry and test conditions in order to provide a direct comparison.

**Table 1. Electrical Characteristics @ Tj = 25°C, Post Total Dose Irradiation** ⑤⑥

	Parameter	100K Rads(Si) <sup>1</sup>		300 K Rads (Si) <sup>2</sup>		Units	Test Conditions
		Min	Max	Min	Max		
BV <sub>DSS</sub>	Drain-to-Source Breakdown Voltage	-200	—	-200	—	V	V <sub>GS</sub> = 0V, I <sub>D</sub> = -1.0mA
V <sub>GS(th)</sub>	Gate Threshold Voltage	-2.0	-4.0	-2.0	-5.0		V <sub>GS</sub> = V <sub>DS</sub> , I <sub>D</sub> = -1.0mA
I <sub>GSS</sub>	Gate-to-Source Leakage Forward	—	-100	—	-100	nA	V <sub>GS</sub> = -20V
I <sub>GSS</sub>	Gate-to-Source Leakage Reverse	—	100	—	100		V <sub>GS</sub> = 20 V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	—	-25	—	-25	μA	V <sub>DS</sub> = -160V, V <sub>GS</sub> = 0V
R <sub>DS(on)</sub>	Static Drain-to-Source On-State Resistance (TO-3)	—	0.317	—	0.317	Ω	V <sub>GS</sub> = -12V, I <sub>D</sub> = -9.0A
R <sub>DS(on)</sub>	Static Drain-to-Source On-State Resistance (SMD-1)	—	0.315	—	0.315	Ω	V <sub>GS</sub> = -12V, I <sub>D</sub> = -9.0A
V <sub>SD</sub>	Diode Forward Voltage ④	—	-3.6	—	-3.6	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = -14A

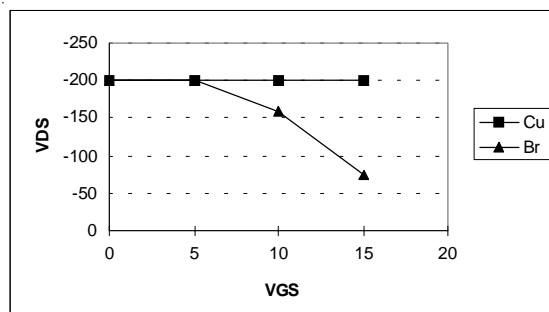
1. Part number IRHN9250 (JANSR2N7423U)

2. Part numbers IRHN93250 (JANSF2N7423U)

International Rectifier radiation hardened MOSFETs have been characterized in heavy ion environment for Single Event Effects (SEE). Single Event Effects characterization is illustrated in Fig. a and Table 2.

**Table 2. Single Event Effect Safe Operating Area**

Ion	LET MeV/(mg/cm <sup>2</sup> )	Energy (MeV)	Range (μm)	V <sub>DS</sub> (V)				
				@V <sub>GS</sub> =0V	@V <sub>GS</sub> =5V	@V <sub>GS</sub> =10V	@V <sub>GS</sub> =15V	@V <sub>GS</sub> =20V
Cu	28.0	285	43	-200	-200	-200	-200	—
Br	36.8	305	39	-200	-200	-160	-75	—



**Fig a. Single Event Effect, Safe Operating Area**

For footnotes refer to the last page

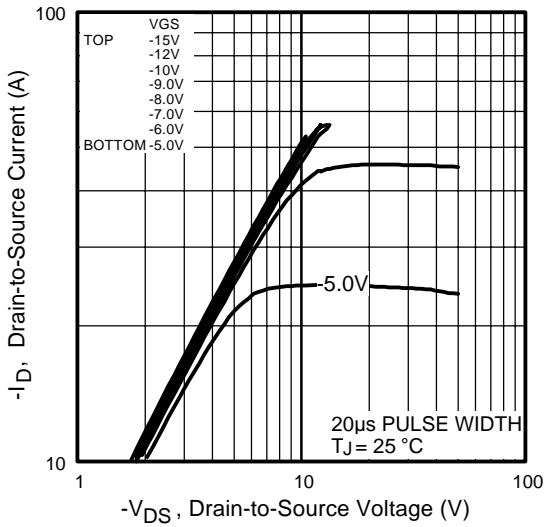


Fig1. Typical Output Characteristics

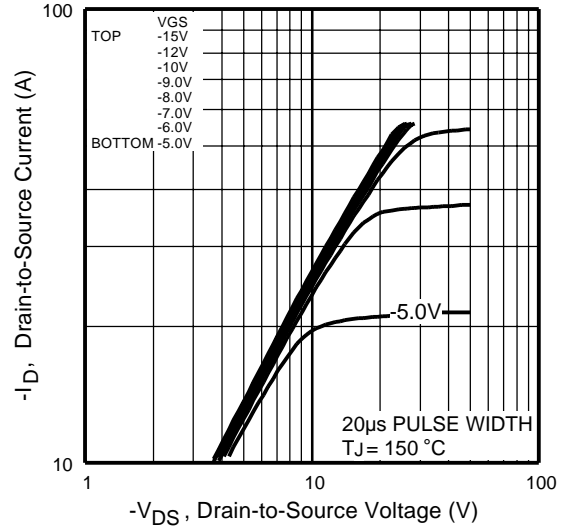


Fig2. Typical Output Characteristics

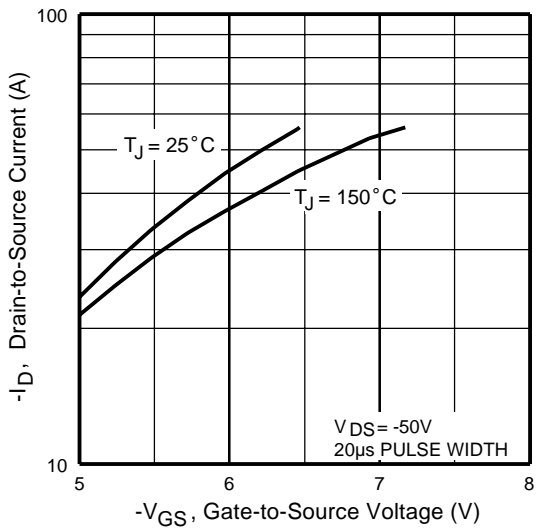


Fig3. Typical Transfer Characteristics

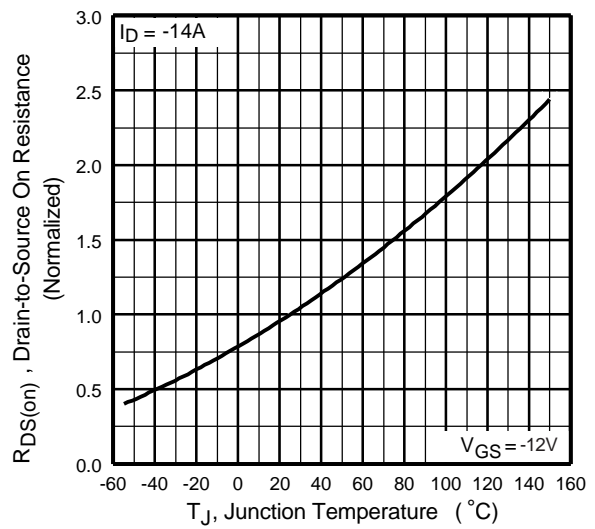


Fig4. Normalized On-Resistance Vs. Temperature

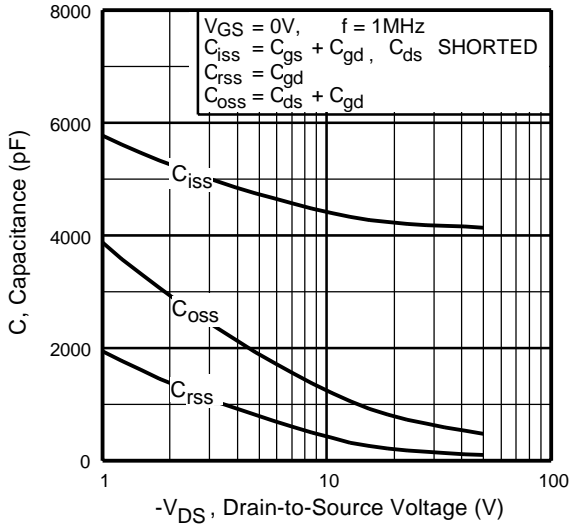


Fig5. Typical Capacitance Vs. Drain-to-Source Voltage

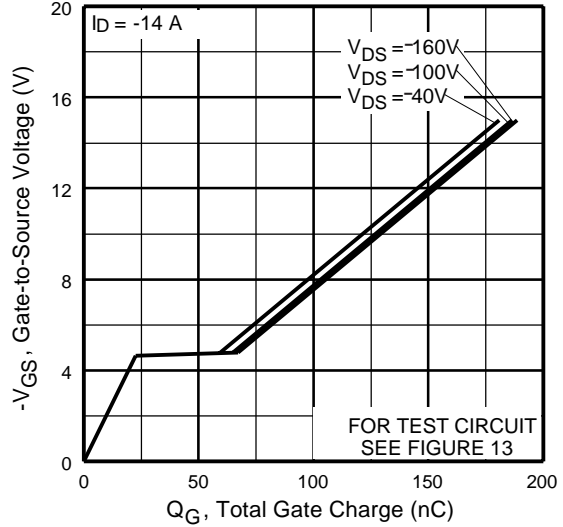


Fig6. Typical Gate Charge Vs. Gate-to-Source Voltage

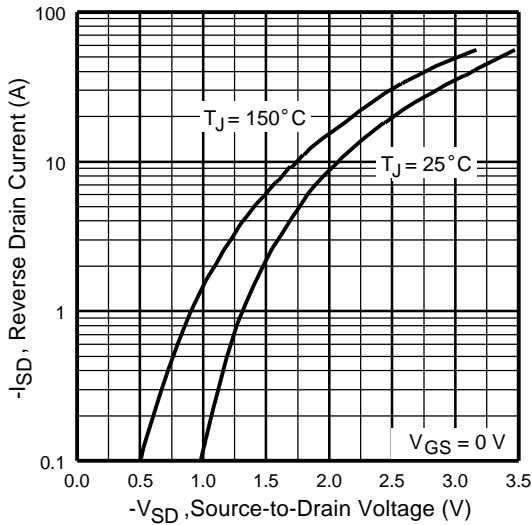


Fig7. Typical Source-Drain Diode Forward Voltage

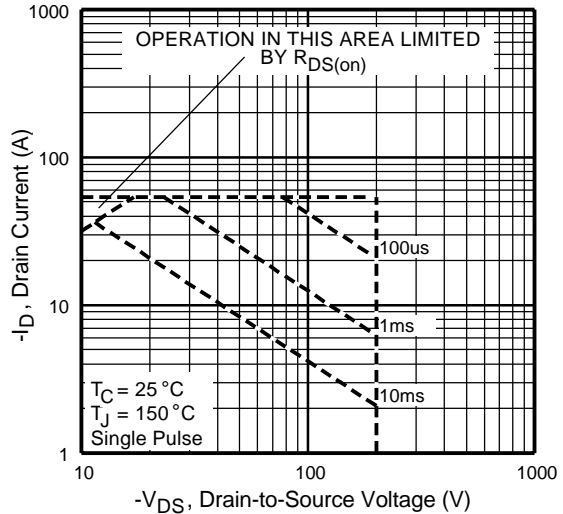


Fig8. Maximum Safe Operating Area

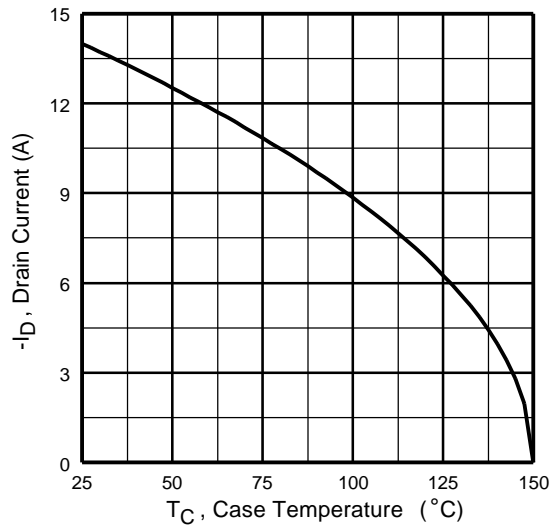


Fig9. Maximum Drain Current Vs. Case Temperature

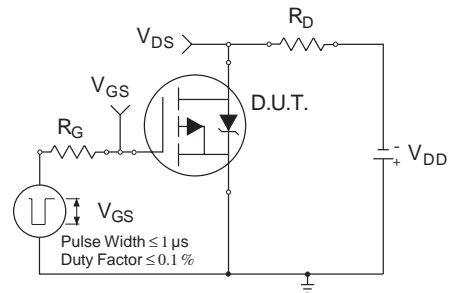


Fig10a. Switching Time Test Circuit

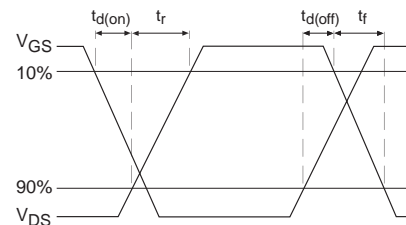


Fig10b. Switching Time Waveforms

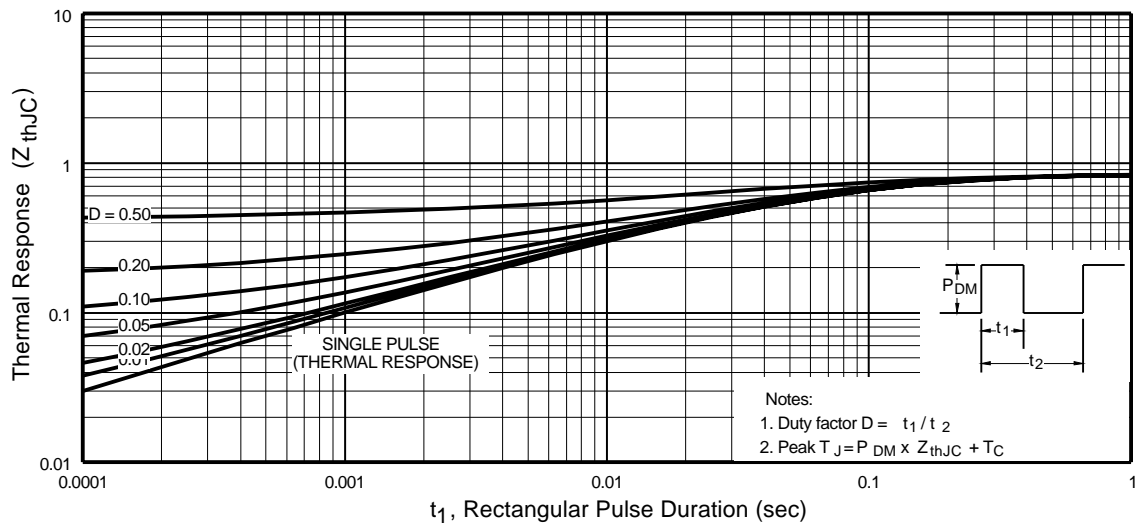


Fig11. Maximum Effective Transient Thermal Impedance, Junction-to-Case

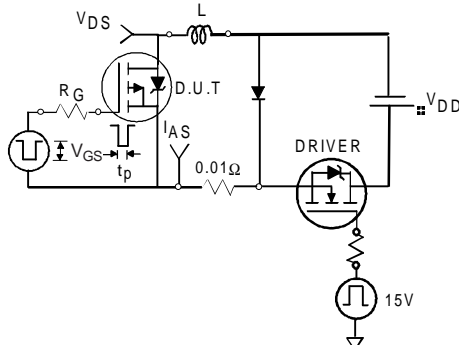


Fig12a. Unclamped Inductive Test Circuit

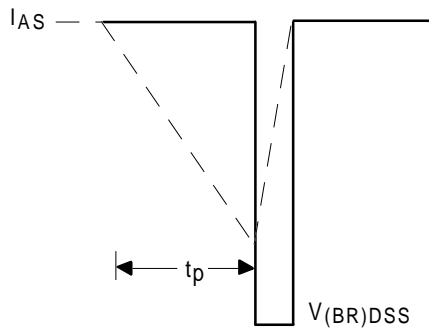


Fig12b. Unclamped Inductive Waveforms

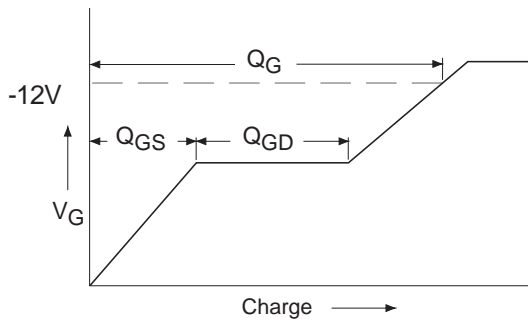


Fig13a. Basic Gate Charge Waveform

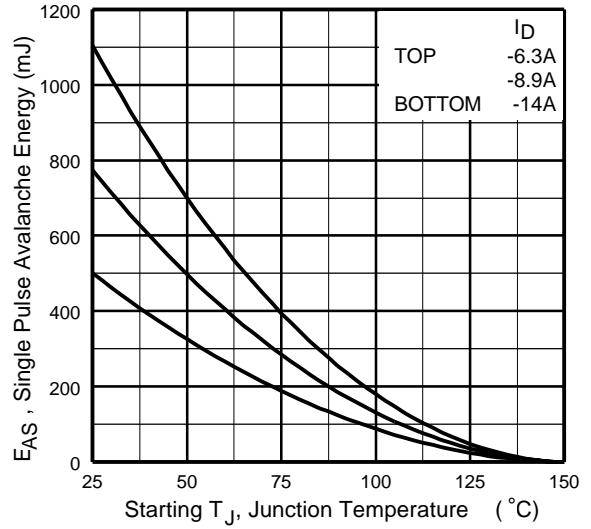


Fig12c. Maximum Avalanche Energy Vs. Drain Current

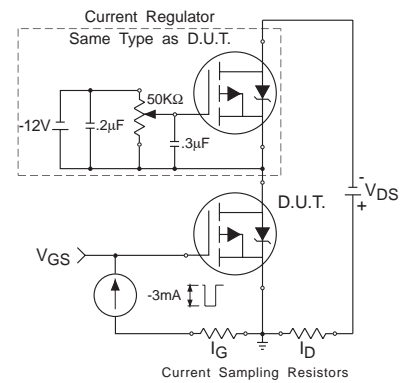
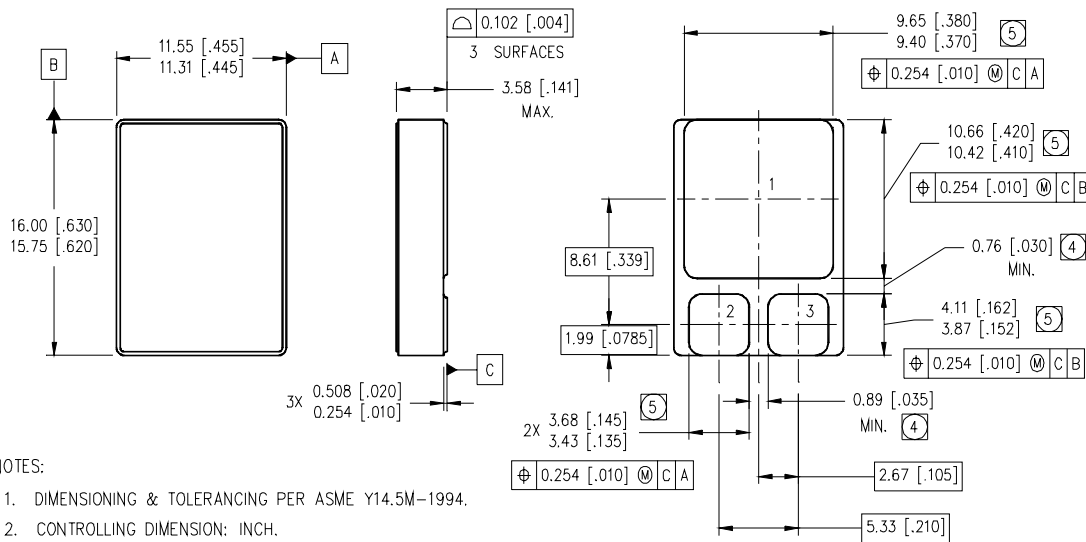


Fig13b. Gate Charge Test Circuit

**Foot Notes:**

- ① Repetitive Rating; Pulse width limited by maximum junction temperature.
- ②  $V_{DD} = -50V$ , starting  $T_J = 25^\circ C$ ,  $L = 5.1mH$   
Peak  $I_L = -14A$ ,  $V_{GS} = -12V$
- ③  $ISD \leq -14A$ ,  $di/dt \leq -600A/\mu s$ ,  
 $V_{DD} \leq -200V$ ,  $T_J \leq 150^\circ C$
- ④ Pulse width  $\leq 300 \mu s$ ; Duty Cycle  $\leq 2\%$
- ⑤ **Total Dose Irradiation with VGS Bias.**  
-12 volt  $V_{GS}$  applied and  $V_{DS} = 0$  during irradiation per MIL-STD-750, method 1019, condition A.
- ⑥ **Total Dose Irradiation with VDS Bias.**  
-160 volt  $V_{DS}$  applied and  $V_{GS} = 0$  during irradiation per MIL-STD-750, method 1019, condition A.

**Case Outline and Dimensions — SMD-1**



NOTES:

1. DIMENSIONING & TOLERANCING PER ASME Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
- ④ DIMENSION INCLUDES METALLIZATION FLASH.
- ⑤ DIMENSION DOES NOT INCLUDE METALLIZATION FLASH.

**PAD ASSIGNMENTS**

- 1 = DRAIN
- 2 = GATE
- 3 = SOURCE

International  
**IR** Rectifier

IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105  
TAC Fax: (310) 252-7903

Visit us at [www.irf.com](http://www.irf.com) for sales contact information.  
Data and specifications subject to change without notice. 06/03